

AH173-WG-7-A AH173-WG-7-B AH175-WG-7-A AH175-WG-7-B AH1800-WG-7 AH1801-WG-7 AH1802-WG-7 AH1803-WG-7 AH180-WG-7 AH182-WG-7 AH183-WG-7 AH337-WG-7
 AH373-WG-7 AH375-WG-7 AHT1803-WG-7 AP130-15RG-7 AP130-15WG-7 AP130-18RG-7 AP130-18WG-7 AP130-20RG-7 AP130-20WG-7 AP130-25RG-7 AP130-25WG-7 AP130-28RG-7
 AP130-28WG-7 AP130-30RG-7 AP130-30WG-7 AP130-33RG-7 AP130-33WG-7 AP130-35RG-7 AP130-35WG-7 AP1701AWG-7 AP1701BWG-7 AP1701CWG-7 AP1701DWG-7
 AP1701EWG-7 AP1701FWG-7 AP1701GWG-7 AP1702AWG-7 AP1702BWG-7 AP1702CWG-7 AP1702DWG-7 AP1702EWG-7 AP1702FWG-7 AP1702GWG-7 AP1703AWG-7 AP1703BWG-7
 AP1703CWG-7 AP1703DWG-7 AP1703EWG-7 AP1703FWG-7 AP1703GWG-7 AP1704AWG-7 AP1704BWG-7 AP1704CWG-7 AP1704DWG-7 AP1704EWG-7 AP1704FWG-7
 AP1704GWG-7 AP431ARG-7 AP431AWG-7 AP431RG-7 AP431WG-7 ATS137-WG-7-A AP130-15SAG-7 AP130-18SAG-7 AP130-20SAG-7 AP130-25SAG-7 AP130-28SAG-7 AP130-30SAG-7
 AP130-33SAG-7 AP130-35SAG-7 AP431ASAG-7 AP431ASRG-7 AP431SAG-7 AP431SRG-7 AP432ASAG-7 AP432ASRG-7 AP432SAG-7 AP432SRG-7

Part Number: **Analog SC59 See List above**
 Weight (mg): 14.08

p = package designator
 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.2763	0.6021	1000000	42763
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	36.1570	5.0909	992600	358894
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	976
		Sn	7440-31-5	0.25%			2500	904
		Zn	7440-66-6	0.22%			2200	795
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.8878	0.125	1000000	8878
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.4233	0.0596	1000000	4233
Encapsulation	EME-G600	Epoxy Resin	-----	5.00%	56.8075	7.9985	50000	28404
		Phenol Resin	-----	5.00%			50000	28404
		Bismuth/Bismuth compound	-----	1.00%			10000	5681
		SiO2	60676-86-0	86.50%			865000	491385
		Cresol Novolac	29690-82-2	2.00%			20000	11362
		C	1333-86-4	0.50%			5000	2840
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	0.7358	0.1036	750000	5518
		epoxy resin	Trade secret	20.00%			200000	1472
		curing agent & hardener	Trade secret	5.00%			50000	368
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.7124	0.1003	1000000	7124
Total					100.00	14.08		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness. Compliance to RoHS is confirmed by third party lab test results. Tests are conducted approximately annually.

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

- | | |
|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |